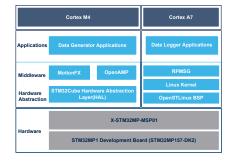




## STM32 MPU OpenSTLinux software expansion package for MEMS Application



### **Features**

- Complete software to build applications using the following sensors using Cortex® M4 and Cortex® A7 of STM32MPU
  - motion Sensors : ISM330DHCX, IIS2DLPC, IIS2MDC
  - pressure sensor: LPS22HHtemperature sensor: STTS22H
- Sample Application for MEMS Sensor fusion running on Cortex® M4
- Sample Application for MEMS data logging on Cortex® A7
- Free, user-friendly license terms

### **Description**

X-LINUX-MEMS1 is a software package for running MEMS sensor fusion - motion FX on STM32MP157F-DK2.

The package provides an example of running MEMS sensor fusion on a Cortex® M4, and sending data over Linux® remote processor messaging (RPMsg) to Cortex® A7 to display console application.

The software package uses the X-STM32MP-MSP01 board mounted on STM32MP157F-DK2 via 40 pin GPIO header.

Product summary		
STM32 MPU OpenST Linux software expansion package for MEMS Application	X-LINUX-MEMS1	
Discovery kit with STM32MP157F MPU	STM32MP157F- DK2	
STM32MP expansion board for motion MEMS, environmental, ToF, and ALS sensor applications	X-STM32MP- MSP01	
Applications	Personal Electronics/ Wearable/IoT, Smart Home	



# **Revision history**

Table 1. Document revision history

Date	Version	Changes
05-May-2023	1	Initial release.

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